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Claims

1. A vertical-cavity device comprising:
 - (a) a chip comprising an active semiconductor layer for providing optical gain;
 - (b) a first mirror arranged on a first side of the active layer;
 - (c) a second mirror arranged on a second side of the active layer, opposite to the first mirror, and forming with at least the first mirror an optically resonant cavity that passes through the active layer in a direction out of the plane of the active layer;
 - (d) a heatspreader for removing heat from the active layer, the heatspreader being arranged inside the cavity and having a first surface adjacent to the chip and a second surface opposite to the first surface, the heatspreader being transparent to light of wavelengths in an operating bandwidth of the device; characterised in that, in addition to removing heat from the active layer, the heatspreader also has one or more further selected property that has a further selected effect on light output from the device.
2. A device as claimed in claim 1, in which the heatspreader is birefringent and the further selected effect is on the polarisation of the output light.
3. A device as claimed in claim 2, in which the difference Δn between the refractive indices of the heatspreader's slow and fast polarisation axes is greater than 0.01.
4. A device as claimed in claim 2 or claim 3, comprising a further element that limits the output light to a linear polarisation.
5. A device as claimed in any of claims 1 to 4, in which the heatspreader has a nonlinear optical response.

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6. A device as claimed in any preceding claim, in which the shape of the heatspreader provides the further selected effect.
7. A device as claimed in claim 6, in which the second
5 surface of the heatspreader is curved or includes a curved structure.
8. A device as claimed in any preceding claim, in which the heatspreader focuses or defocuses the output light.
9. A device as claimed in any preceding claim, in which
10 the heatspreader focuses pump light into the active layer.
10. A device as claimed in any preceding claim, in which the further selected effect is on light generated in the active semiconductor layer at a fundamental frequency of
15 the device.
11. A device as claimed in any preceding claim, in which the selected property of the heatspreader has been selected to affect the spectrum of the output light.
12. A device as claimed in claim 11, in which the
20 heatspreader has a refractive index that has been selected to provide substantially no refractive index step at the first surface.
13. A device as claimed in claim 12, in which reflectance at the first surface of the heatspreader is
25 less than 5%.
14. A device as claimed in claim 10, in which the heatspreader has a refractive index that has been selected to provide a refractive index step at the first surface.
- 30 15. A device as claimed in any preceding claim, in which the second surface of the heatspreader is at an angle to the layers of the chip.

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16. A device as claimed in any preceding claim, in which the heatspreader has a shape selected to provide control of a spatial mode of the output light.

17. A device as claimed in claim 16, in which the
5 heatspreader focuses or defocuses intracavity light.

18. A device as claimed in claim 17, in which the second mirror is flat.

19. A device as claimed in claim 18 in which the second mirror is a MEMS mirror.

10 20. A device as claimed in any preceding claim, in which the second surface of the heatspreader has a dielectric coating.

21. A device as claimed in claim 20, in which the dielectric coating is an anti-reflection coating.

15 22. A device as claimed in claim 20, in which the dielectric coating is a mirror coating and it forms the second mirror.

23. A device as claimed in any preceding claim in which the heatspreader has a thickness of less than 1.5 mm.

20 24. A device as claimed in any preceding claim, in which the heatspreader is also a loss modulator.

25. A method of manufacturing a vertical-cavity device, comprising:

(a) fabricating a chip comprising an active semiconductor
25 layer for providing optical gain;

(b) providing a first mirror on a first side of the active layer;

(c) providing a second mirror on a second side of the active layer, opposite to the first mirror, which forms
30 with at least the first mirror an optically resonant cavity that passes through the active layer in a direction out of the plane of the active layer;

(d) providing in the cavity a heatspreader for removing heat from the active layer, the heatspreader having a

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first surface adjacent to the chip and a second surface opposite to the first surface, the heatspreader being transparent to light of wavelengths in the operating bandwidth of the device;

5 characterised in that the method also includes the step of selecting one or more property of the heatspreader to have a selected effect on the output light, in addition to the effects of removing heat from the active layer.

26. A method as claimed in claim 25, including the step
10 of forming the second surface of the heatspreader to be curved or to include a curved structure.

27. A method as claimed in claim 26, in which the curved surface is formed by polishing.

28. A method as claimed in claim 26, in which the curved
15 surface or the curved structure is formed by etching.

29. A device manufactured by a method according to any of claims 25 to 28.

30. An amplifier or laser including a source of pump
20 light comprising a device according to any of claims 1 to 24.

31. An amplifier or laser as claimed in claim 30 that is a Raman amplifier.

32. A vertical cavity device comprising:

(a) a chip comprising an active semiconductor layer
25 for providing optical gain;

(b) a first mirror arranged on a first side of the active layer suitable for forming with at least a second mirror arranged on a second side of the active layer, opposite to the first mirror, an optically resonant
30 cavity that passes through the active layer in a direction out of the plane of the active layer; and
(c) a heatspreader for removing heat from the active layer, having a first surface adjacent to the active layer and a second surface opposite to the first surface,

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the heatspreader being transparent to light of wavelengths in an operating bandwidth of the device;

characterised in that, in addition to removing heat from the active layer, the heatspreader also has one or
5 more further selected property that has a further selected effect on light output from the device.